ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Par	PC. Bannockb	ourn. Illinois. A	All rights reserved un ntions.	nder both	This docum level parts, t	ent is a declaration en	n of the substat compasses all l	ces within the manufactures within the manufacture over level materials for v	arer listed which the	item. Note: if manufacturer	the item is an as has engineering	sembly with low responsibility.	
	21.1 IPC Web Site for Information on IPC-1752 Standard Form Thttp://www.ipc.org/IPC-175x Distribution				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informati					on			
Supplier Information													
Company name* Com			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2024-04-20			
Contact Name Title - Contact			ct	Pho		Phone - Contact*			Email	Email - Contact*			
Product-Env-Stewards Product Envir			Enviro Compliance		NA			Produ	Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Represen			sentative		Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards Product E			duct Enviro Compliance		NA			Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	NCP565	NCP565ST12T3G ANA 1		NA 1.5A LDO REGULATOR		2024-04-20 MY1		MY1	IY1 1		mg	Each	
Ianufacturing Proccess Informa	tion												
Terminal Plating / Grid Array M	Interial Terminal Base		Alloy J-STD-020 MSL Ratin		L Rating	Peak Process Body Temperature Max Tim		rature Max Time at Peal	k Temper	ature Numb	er of Reflow Cyc	cles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	3	3		260	С	30	seco	onds 3			
omments													
TTENTION: MSL 3 Rated item require	es Bake and D	ry Pack (after	r electrical test)										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.3	mg	Supplier	Silicon (Si)	7440-21-3		3.3	mg
Die Attach	2.37	mg		Epoxy resin	proprietary data		0.0592	mg
			Supplier	Silver (Ag)	7440-22-4		2.0027	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0592	mg
			Supplier	Inorganic filler	Proprietary Data		0.0592	mg
			Supplier	Dicyandiamine	461-58-5		0.0118	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.1777	mg
Lead Frame	37.17	mg	Supplier	Silver (Ag)	7440-22-4		0.4832	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0372	mg
			Supplier	Iron (Fe)	7439-89-6		0.8921	mg
			Supplier	Copper (Cu)	7440-50-8		35.7575	mg
Mold Compound-Black	59.7	mg		Epoxy resin	proprietary data		2.985	mg
			Supplier	Phenolic Resin	Proprietary Data		2.985	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.194	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2985	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		52.2375	mg
Plating	7.44	mg	Supplier	Tin (Sn)	7440-31-5		7.44	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg